



PART NO. : TG10-DA2N5LF

16PIN SMT ISOLATION MODULE

DESIGNED FOR CIRRUS LOGIC DIGITAL AUDIO
INTERFACE APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE $-40/+85^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @25°C

URNS RATIO

P1-2:P16-15
P7-8:P10-9

1:1 $\pm 2\%$
1:1 $\pm 2\%$

OCL (100KHz,0.1V)
P1-2,P7-8

750 μH nom

DCR P1-2,P7-8

0.5 Ω max

LL P1-2,P7-8

1.0 μH max

Cw/w P1-16,P7-10
(GND P3&P6)

18pF max
9pF max

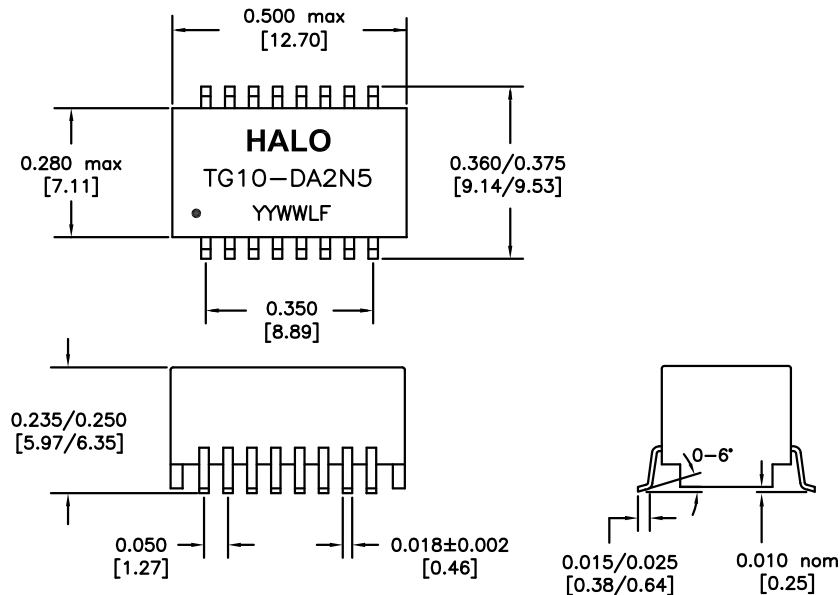
BANDWIDTH (Nominal)

10kHz-200MHz

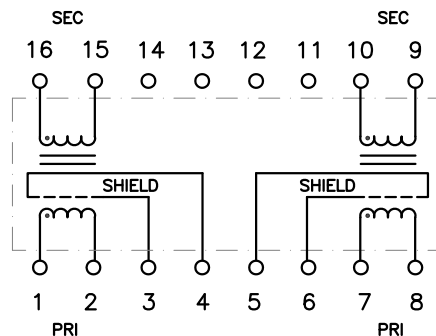
ISOLATION

PRI,SHIELD - SEC
PRI - SHIELD

1,500Vrms
500Vrms



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



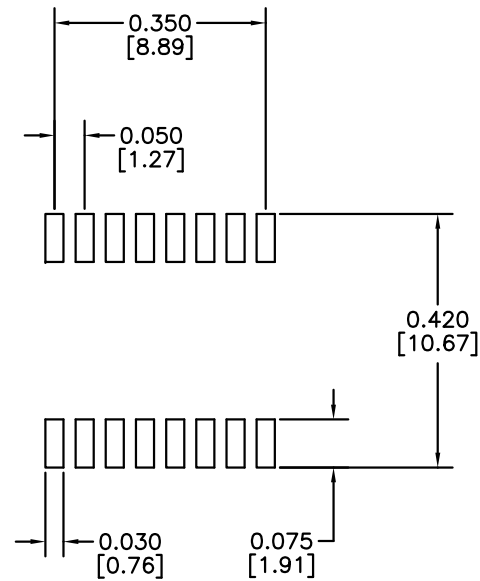
ONLY ONE END OF THE SHIELD CAN BE GROUNDED

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
FOR	CIRRUS LOGIC DIGITAL AUDIO	DRAWN LI ZHI ZHONG	4/27/16	A	PROD. RELEASE	4/27/16
PART NO.	TG10-DA2N5LF	CHECKED LEI KEONG	8/8/16	B	ADD BW SPEC.	5/13/16
SCALE	NONE	APPROVED PETER LU	8/8/16	C	REVISE CKT	5/17/16
PAGE	1 OF 2	FILE DA2N5LF.DWG		D	UPDATE DESC.	8/8/16





RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

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PAGE	2 OF 2					